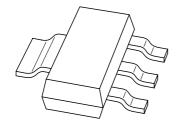
DISCRETE SEMICONDUCTORS

DATA SHEET



PZTA92 PNP high-voltage transistor

Product specification Supersedes data of 1997 May 22 1999 Apr 14



PNP high-voltage transistor

PZTA92

FEATURES

- Low current (max. 100 mA)
- High voltage (max. 300 V).

APPLICATIONS

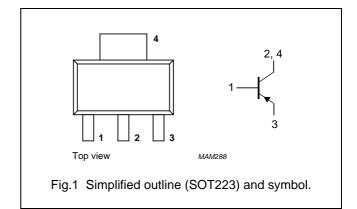
- · Video equipment
- Telephony
- · Professional communication equipment.

DESCRIPTION

PNP high-voltage transistor in a SOT223 plastic package. NPN complement: PZTA42.

PINNING

PIN	DESCRIPTION
1	base
2, 4	collector
3	emitter



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-300	V
V _{CEO}	collector-emitter voltage	open base	-	-300	V
V _{EBO}	emitter-base voltage	open collector	-	-5	V
Ic	collector current (DC)		_	-100	mA
I _{CM}	peak collector current		_	-200	mA
I _{BM}	peak base current		_	-100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	1.2	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	note 1	104	K/W
R _{th j-s}	thermal resistance from junction to soldering point		23	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = -200 V	_	-20	nA
I _{EBO}	emitter cut-off current	$I_C = 0; V_{BE} = -5 \text{ V}$	_	-100	nA
h _{FE}	DC current gain	$I_C = -1 \text{ mA}; V_{CE} = -10 \text{ V}; \text{ note 1}$	25	_	
		$I_C = -10 \text{ mA}; V_{CE} = -10 \text{ V}; \text{ note 1}$	40	_	
		$I_C = -30 \text{ mA}; V_{CE} = -10 \text{ V}; \text{ note 1}$	25	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -20 \text{ mA}; I_B = -2 \text{ mA}$	_	-500	mV
V _{BEsat}	base-emitter saturation voltage	$I_C = -20 \text{ mA}; I_B = -2 \text{ mA}$	_	-900	mV
C _c	collector capacitance	$I_E = 0$; $V_{CB} = -20 \text{ V}$; $f = 1 \text{ MHz}$	_	6	pF
f _T	transition frequency	$I_C = -10 \text{ mA}; V_{CE} = -20 \text{ V}; f = 100 \text{ MHz}$	50	_	MHz

Note

1. Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

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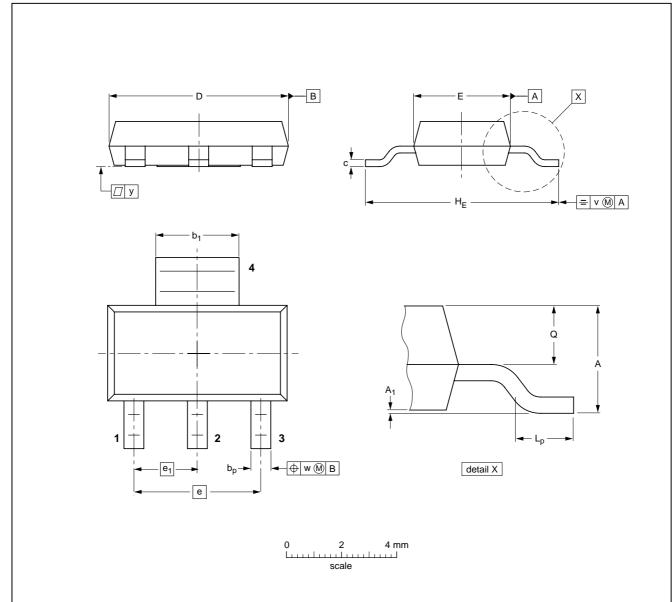
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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	bp	b ₁	С	D	E	е	e ₁	HE	Lp	Q	v	w	у
mm	1.8 1.5	0.10 0.01	0.80 0.60	3.1 2.9	0.32 0.22	6.7 6.3	3.7 3.3	4.6	2.3	7.3 6.7	1.1 0.7	0.95 0.85	0.2	0.1	0.1

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT223			SC-73			97-02-28 99-09-13

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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1999 Apr 14

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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